

PTC thermistors for motor starting

Metallized disks for low power consumption

Series/Type: B595** Date: March 2012

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Low power consumption

Applications

Time delay in turning off the auxiliary winding of single-phase AC motors

Features

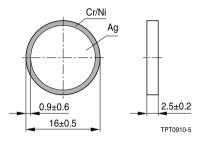
- Metallization: CrNi (sputtered) + Ag (screen-printed)
- Excellent long-term reliability
- Suitable for clamp contacting
- UL approval to UL 1434 (file number E69802)
- RoHS-compatible

Delivery mode

Bulk

General technical data

Dimensional drawing



Switching cycles		Ν	> 100000		
Operating temperature range	(V = 0)	T _{op}	+5/+80	°C	
Operating temperature range	$(V = V_{max})$	Top	+5/+80	°C	

Electrical specifications and ordering codes

Туре	I _{max}	V _{max}	T _{ref}	ts1)	$V_{BD}^{2)}$	$R_R \pm \Delta R_R$	Ordering code
			(typ.)			$(V_{PTC} \le 2.5 \text{ V})$	
	А	V	°C	S	V	Ω	
$V_{R} = 120$) V _{RMS}						
A536	10	200	135	0.30	> 400	10 ±20%	B59536A0135A020
A546	12	180	135	0.45	> 360	4.70 ±20%	B59546A0135A020
A548	12	200	135	0.30	> 400	6.80 ±20%	B59548A0135A020
$V_{R} = 230$	V _{RMS}						
A549	8	350	135	0.30	> 640	22 ±20%	B59549A0135A020
A550	8	355	135	0.25	> 700	33 ±20%	B59550A0135A020
A556	8	350	135	0.35	> 600	15 ±20%	B59556A0135A020

1) Measured at V = V_{max} and I = 0.8 \cdot I_{max}

2) PTC clamped between points.



Low power consumption

Reliability data

Test ¹⁾	Standard	Test conditions	$ \Delta R_{25}/R_{25} $
Electrical endurance,	IEC 60738-1	Room temperature, V _{max} ; I _{max}	< 25%
cycling		Number of cycles: 500 000	
Electrical endurance,	IEC 60738-1	Storage at V _{max} /T _{op,max} (V _{max})	< 25%
constant		Test duration: 1000 h	
Damp heat	IEC 60738-1	Temperature of air: 40 °C	< 20%
		Relative humidity of air: 93%	
		Duration: 56 days	
		Test according to IEC 60068-2-78	
Rapid change	IEC 60738-1	$T_1 = T_{op,min} (0 V), T_2 = T_{op,max} (0 V)$	< 20%
of temperature		Number of cycles: 5	
		Test duration: 30 min	
		Test according to IEC 60068-2-14, test Na	
Climatic sequence	IEC 60738-1	Dry heat: $T = T_{op,max} (0 V)$	< 25%
		Test duration: 16 h	
		Damp heat first cycle	
		Cold: $T = T_{op,min} (0 V)$	
		Test duration: 2 h	
		Damp heat 5 cycles	
		Tests performed according to	
		IEC 60068-2-30	

¹⁾ All tests with PTC disk mounted in EPCOS housing.



Low power consumption

Cautions and warnings

General

- EPCOS thermistors are designed for specific applications and should not be used for purposes not identified in our specifications, application notes and data books unless otherwise agreed with EPCOS during the design-in-phase.
- Ensure suitability of thermistor through reliability testing during the design-in phase. The thermistors should be evaluated taking into consideration worst-case conditions.

Storage

- Store thermistors only in original packaging. Do not open the package before storage.
- Storage conditions in original packaging: storage temperature -25 °C ... +45 °C, relative humidity ≤75% annual mean, maximum 95%, dew precipitation is inadmissible.
- Avoid contamination of thermistors surface during storage, handling and processing.
- Avoid storage of thermistor in harmful environment with effect on function on long-term operation (examples given under operation precautions).
- Use thermistor within the following period after delivery:
 - Through-hole devices (housed and leaded PTCs): 24 months
 - Motor protection sensors, glass-encapsulated sensors and probe assemblies: 24 months
 - Telecom pair and quattro protectors (TPP, TQP): 24 months
 - Leadless PTC thermistors for pressure contacting: 12 months
 - Leadless PTC thermistors for soldering: 6 months
 - SMDs in EIA sizes 3225 and 4032, and for PTCs with metal tags: 24 months
 - SMDs in EIA sizes 0402, 0603, 0805 and 1210: 12 months

Handling

- PTCs must not be dropped. Chip-offs must not be caused during handling of PTCs.
- Components must not be touched with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.

Soldering (where applicable)

- Use rosin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.
- Standard PTC heaters are not suitable for soldering.

Low power consumption

Mounting

- Electrode must not be scratched before/during/after the mounting process.
- Contacts and housing used for assembly with thermistor have to be clean before mounting. Especially grease or oil must be removed.
- When PTC thermistors are encapsulated with sealing material, the precautions given in chapter "Mounting instructions", "Sealing and potting" must be observed.
- When the thermistor is mounted, there must not be any foreign body between the electrode of the thermistor and the clamping contact.
- The minimum force of the clamping contacts pressing against the PTC must be 10 N.
- During operation, the thermistor's surface temperature can be very high. Ensure that adjacent components are placed at a sufficient distance from the thermistor to allow for proper cooling at the thermistors.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of thermistor. Be sure that surrounding parts and materials can withstand this temperature.
- Avoid contamination of thermistor surface during processing.

Operation

- Use thermistors only within the specified temperature operating range.
- Use thermistors only within the specified voltage and current ranges.
- Environmental conditions must not harm the thermistors. Use thermistors only in normal atmospheric conditions. Avoid use in deoxidizing gases (chlorine gas, hydrogen sulfide gas, ammonia gas, sulfuric acid gas etc), corrosive agents, humid or salty conditions. Contact with any liquids and solvents should be prevented.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by abnormal function (e.g. use VDR for limitation of overvoltage condition).



Low power consumption

Symbols and terms

А	Area
С	Capacitance
C _{th}	Heat capacity
f	Frequency
I	Current
I _{max}	Maximum current
I _R	Rated current
I _{res}	Residual current
I _{PTC}	PTC current
l _r	Residual currrent
l _{r,oil}	Residual currrent in oil (for level sensors)
I _{r,air}	Residual currrent in air (for level sensors)
I _{RMS}	Root-mean-square value of current
l _s	Switching current
I _{Smax}	Maximum switching current
LCT	Lower category temperature
Ν	Number (integer)
N _c	Operating cycles at V_{max} , charging of capacitor
N _f	Switching cycles at V_{max} , failure mode
Р	Power
P ₂₅	Maximum power at 25 °C
P _{el}	Electrical power
P_{diss}	Dissipation power
R _G	Generator internal resistance
R _{min}	Minimum resistance
R _R	Rated resistance
ΔR_{R}	Tolerance of R _R
R _P	Parallel resistance
R _{PTC}	PTC resistance
R _{ref}	Reference resistance
Rs	Series resistance
R ₂₅	Resistance at 25 °C
R _{25,match}	Resistance matching per reel/ packing unit at 25 °C
ΔR_{25}	Tolerance of R ₂₅
Т	Temperature
t T	Time
T _A	Ambient temperature
t _a	Thermal threshold time



Low power consumption

Tc	Ferroelectric Curie temperature
t _E	Settling time (for level sensors)
T _R	Rated temperature
T _{sense}	Sensing temperature
T _{op}	Operating temperature
T _{PTC}	PTC temperature
t _R	Response time
T _{ref}	Reference temperature
T _{Rmin}	Temperature at minimum resistance
t _s	Switching time
T _{surf}	Surface temperature
UCT	Upper category temperature
V or V_{el}	Voltage (with subscript only for distinction from volume)
V _{c(max)}	Maximum DC charge voltage of the surge generator
$V_{F,max}$	Maximum voltage applied at fault conditions in protection mode
V _{RMS}	Root-mean-square value of voltage
V _{BD}	Breakdown voltage
V _{ins}	Insulation test voltage
$V_{link,max}$	Maximum link voltage
V _{max}	Maximum operating voltage
$V_{max,dyn}$	Maximum dynamic (short-time) operating voltage
V _{meas}	Measuring voltage
V _{meas,max}	Maximum measuring voltage
V _R	Rated voltage
V _{PTC}	Voltage drop across a PTC thermistor
α	Temperature coefficient
Δ	Tolerance, change
δ_{th}	Dissipation factor
$ au_{th}$	Thermal cooling time constant
λ	Failure rate
e	Lead spacing (in mm)

Abbreviations / Notes

SMD Surface-mount devices

* To be replaced by a number in ordering codes, type designations etc.

+ To be replaced by a letter

All dimensions are given in mm.

The commas used in numerical values denote decimal points.

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